

### FEATURES

- ✧ For surface mount applications
- ✧ Easy pick and place
- ✧ Ultra fast recovery times for high efficiency
- ✧ Low forward voltage, low power loss
- ✧ Built-in strain relief, ideal for automated placement
- ✧ High temperature soldering: 250°C/10 seconds on terminals
- ✧ Plastic package has underwriters laboratories flammability classification 94V-0

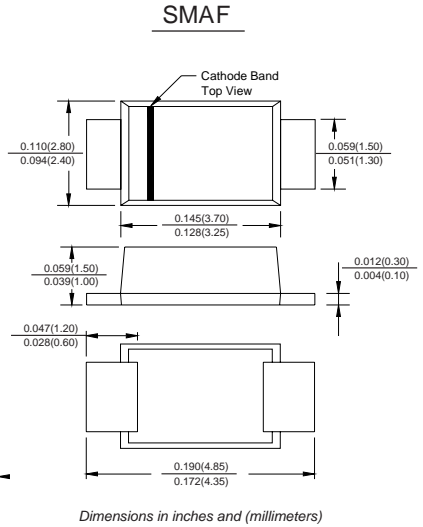
### MECHANICAL DATA

- ✧ Case: JEDEC SMAFL, molded plastic body over passivated chip
- ✧ Terminals: Solder Plated, solderable per MIL-STD-750, Method 2026
- ✧ Polarity: Color band denotes cathode end

### Marking Information



**LGE: Lu Guang Electronic XXXX:**  
marking code (US2AF-US2MF)



### Maximum Ratings (@TA = 25°C unless otherwise specified)

Characteristic	Symbol	US2AF	US2BF	US2DF	US2GF	US2JF	US2KF	US2MF	UNITS
Maximum recurrent peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RWS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L=90^\circ\text{C}$	$I_{F(AV)}$	2.0							A
Peak forward surge current 8.3ms single half sine-wave super imposed on rated load	$I_{FSM}$	50							A

### Thermal Characteristics

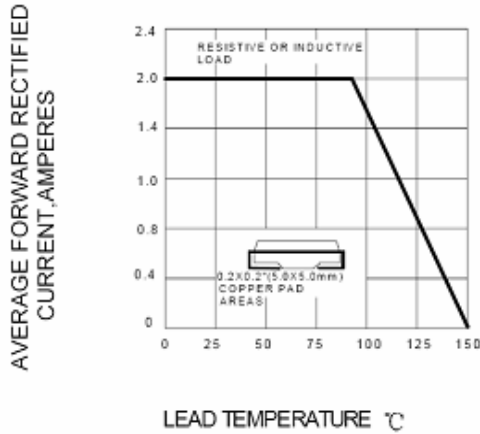
Characteristic	Symbol	US2AF	US2BF	US2DFA	US2GF	US2JF	US2KF	US2MF	UNITS
Typical junction capacitance at 4.0V, 1MHz	$C_J$	50				30			pF
Maximum thermal resistance (NOTE1)	$R_{\theta JA}$	40							°C/W
	$R_{\theta JL}$	15							
Operating temperature range	$T_J$	-55----- +150							°C
Storage temperature range	$T_{STG}$	-55----- +150							°C

### Electrical Characteristics (@TA = 25°C unless otherwise specified)

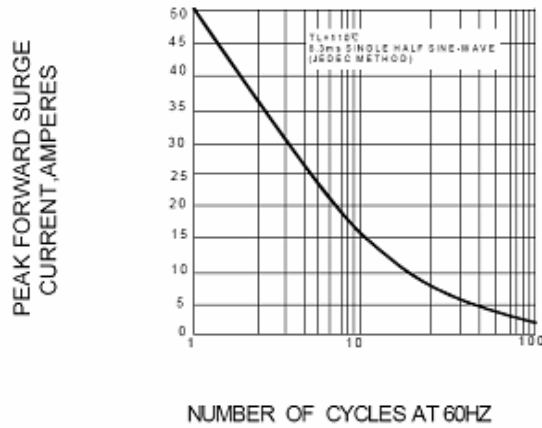
Characteristic	Symbol	US2AF	US2BF	US2DF	US2GF	US2JF	US2KF	US2MF	UNITS	
Maximum instantaneous forward voltage at 2.0A	$V_F$	1.0			1.25	1.7			V	
Maximum DC reverse current @ $T_A=25^\circ\text{C}$ at rated DC blocking voltage @ $T_A=125^\circ\text{C}$	$I_R$	10.0				350				$\mu\text{A}$
		50				75				
Maximum reverse recovery time at $I_F=0.5\text{A}$ $I_R=1.0\text{A}$ $I_{rr}=0.25\text{A}$	$t_{rr}$	50				75				ns

NOTE: 1.P.C.B.mounted on 0.2X0.2"(5.0X5.0mm) copper pad area

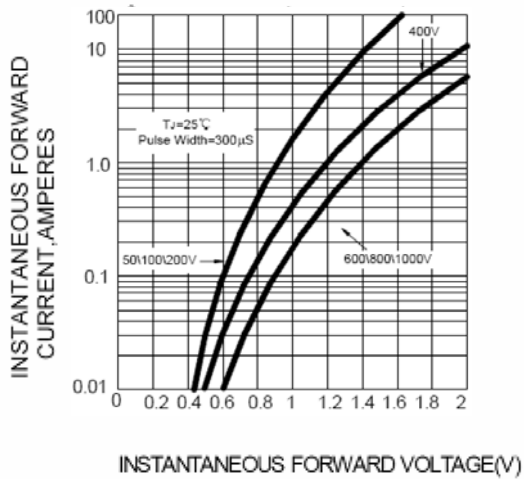
**FIG.1 – FORWARD CURRENT DERATING CURVE**



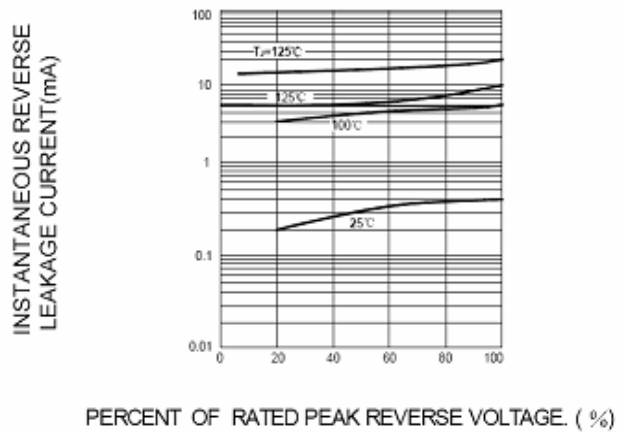
**FIG.2 – MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT**



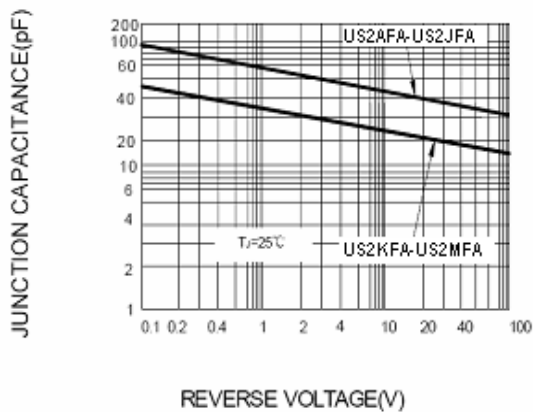
**FIG.3 – TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS**



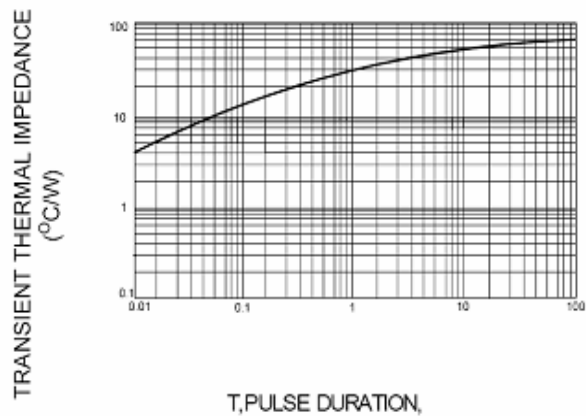
**FIG.4 – TYPICAL REVERSE CHARACTERISTICS**



**FIG.5 – TYPICAL JUNCTION CAPACITANCE**



**FIG.6 – TYPICAL TRANSIENT THERMAL IMPEDANCE**



PACKAGE	SPQ/PCS	CARTON SPQ/PCS	CARTON SIZE/CM	CARTON GW/KG	CARTON NW/KG
SMA	5000/REEL	80000	36X30.6X31	12.00	11.00